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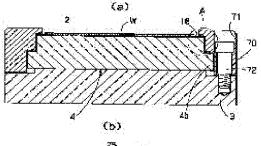
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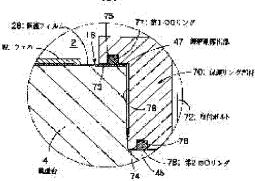
(54) ELECTROSTATIC CHUCK DEVICE AND MOUNTING BLOCK

(57)Abstract:

PROBLEM TO BE SOLVED: To prevent corrosion on an exposed part of a high polymer adhesive or low-melting point metal for fixing a chuck body, and to excellently maintain uniformity in treatment.

SOLUTION: This device includes a chuck body 16 having a conductive film applied with a voltage at the time of attracting a treated work W and a pair of insulative films sandwiching the conductive film from both sides. The chuck body 16 is stuck on a surface of a mounting block 4 with a high polymer adhesive or low-melting point metal, while an exposed part 47 of the exposed high polymer adhesive or low-melting point metal in a peripheral position of the chuck body 16 is airtightly isolated form an inner space of a treatment chamber 2 by a protection ring member 70 made of a fluorine-based resin. The protection ring member 70 is fixed within the treatment chamber 2 with attaching bolts 72 inserted into bolt holes 71 formed in the protection ring member 70.





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